

**REMARKS**

Applicants have amended their drawings in order to provide the legend “CONVENTIONAL” for Fig. 1. Such term “CONVENTIONAL” is consistent with the description in Applicants’ specification as originally filed, e.g., at page 11, line 12. In view of this amendment of Fig. 1, it is respectfully submitted that the objection to the drawings, set forth in Item 2 on page 2 of the Office Action mailed October 5, 2011, is moot, and that the required corrected drawing has been submitted.

Applicants have amended the title to be “clearly indicative of the invention to which the claims being considered on the merits in the above-identified application are directed”. In view of this new title, it is respectfully submitted that the requirement for a new title, set forth in Item 3 on page 2 of the Office Action mailed October 5, 2011, has been satisfied.

Applicants have amended their claims in order to further clarify the definition of various aspects of the present invention. Specifically, Applicants have cancelled claims 1, 3-10, 13 and 14 without prejudice or disclaimer, are adding new claims 23-34, and have amended dependencies of claims 15-22 in light of the newly added claims. Specifically, of the newly added claims, claims 23, 27, 33 and 34 are independent claims, directed to a method of manufacturing an electronic device that includes (1) an IC chip having two external electrodes, the external electrodes being formed respectively on one and the other of the faces of an opposing pair of faces of the IC chip, (2) a transmission and reception antenna having a slit formed therein, and (3) a bridging plate that electrically connects the IC chip and the antenna, the transmission and reception antenna being on a base substrate. Claim 23 recites that the manufacturing method includes arranging a plurality of IC chips in at least one of

a longitudinal orientation or a horizontal orientation; positionally aligning at least one of the plurality of IC chips at a position corresponding to a determined position on an antenna circuit on which the at least one of the plurality of IC chips is being mounted, the at least one of the plurality of IC chips being positioned onto an anisotropic conductive adhesive layer; and performing thermal compression bonding that joins the bridging plate on the transmission and reception antenna such that the bridging plate spans the slit and electrically connects the IC chip and the antenna. The other independent claims, claims 27, 33 and 34, respectively recite processing steps corresponding to those in claims 2, 3 and 4.

Of the remaining newly added claims, which are dependent claims, note previously considered claims 13 and 14 in connection with claims 24 and 25, respectively; note previously considered claim 6 in connection with claim 26; and in connection with claims 28-32, note previously considered claims 6-10, respectively.

The rejection of claims 1 and 5 under the second paragraph of 35 USC 112, set forth in Items 5-7 on page 3 of the Office Action mailed October 5, 2011, is respectfully traversed, insofar as applicable to the claims presently in the application. Thus, comparing claim 23 with previously considered claim 1, it is noted that claim 23 does not include the passage quoted by the Examiner in Item 6 on page 3 of the Office Action mailed October 5, 2011. Accordingly, the basis for rejection of claim 1 is moot, insofar as applicable to claim 23.

With respect to the basis for rejection of claim 5 under the second paragraph of 35 USC 112, attention is respectfully directed to claim 26, dependent on claim 23. It is respectfully submitted that claim 23 sets forth the relationship of the IC chip, the transmission and reception antenna having a slit formed therein and the bridging

plate that electrically connects the IC chip and the antenna. Accordingly, it is respectfully submitted that it is clear how such structures are interrelated with each other. In connection with the anisotropic conductive adhesive layer, it is respectfully submitted that claim 26 recites thermal compression bonding “that joins the bridging plates on the IC chips and the antenna substrate” via an anisotropic conductive adhesive layer. It is respectfully submitted that claim 26 clearly defines structure (positioning) and function of the anisotropic conductive adhesive layer, such that the interrelationship of this layer with respect to the other structure is sufficiently definite so as to satisfy requirements the second paragraph of 35 USC 112 in connection therewith. Furthermore, it is respectfully submitted that in light of the first processing sub-paragraph of claim 26, the “antenna substrate” is sufficiently clear so as to satisfy requirements of the second paragraph of 35 USC 112.

Applicants respectfully submit that all of the claims presented for consideration by the Examiner patentably distinguish over the teachings of the documents cited by the Examiner in rejecting claims in the Office Action mailed October 5, 2011, that is, the teachings of the U.S. patent documents to Usami, Patent Application Publication No. 2004/0061613 (Usami '613), to Usami, Patent Application Publication No. 2005/0134460 (Usami '460), and to Mosher, et al., Patent Application Publication No. 2003/0173408, under the provisions of 35 USC 102 and 35 USC 103.

Initially, attention is respectfully directed to the earliest date, for prior art purposes, of Usami '460, that is, December 3, 2004. Such date of December 3, 2004 is the date, for purposes of prior art, of Usami '460, under 35 USC 102(e).

However, note that the above-identified application is a National Stage application filed under 35 USC 371 of International (PCT) Application No. PCT/JP2004/017939, with an international filing date of December 2, 2004. Thus, it is respectfully submitted that the above-identified application has an effective filing date of December 2, 2004. See 35 USC 363; note also Manual of Patent Examining Procedure (MPEP) 1893.03(b). As can be appreciated, the effective filing date of the above-identified application, December 2, 2004, is prior to the earliest prior art date of Usami '460 (that is, December 3, 2004). Accordingly, it is respectfully submitted that Usami '460 does not constitute prior art in connection with the above-identified application. As Usami '460 does not constitute prior art in connection with the presently claimed subject matter, and this document is the sole document or primary document applied in the rejections under 35 USC 102 and 35 USC 103, clearly the rejections under 35 USC 102 and 35 USC 103 in the Office Action mailed October 5, 2011, must fall on this basis alone. For purposes of conciseness, and while Applicants do not agree with contentions by the Examiner on pages 3-12 of the Office Action mailed October 5, 2011, in view of the clear impropriety of the rejections under 35 USC 102 and 35 USC 103, since Usami '460 is not prior art, no further discussion of these rejections are set forth herein.

The contention by the Examiner in Item 9 on page 3 of the Office Action mailed October 5, 2011, that Usami '460 is prior art under 35 USC 102(b), is simply incorrect. Usami '460 has prior art dates under 35 USC 102(a), (b) and (e) after the effective filing date of the above-identified application, and thus does not qualify as prior art with respect to the presently claimed invention under any of 35 USC 102(a), (b) or (e).

In view of the foregoing comments and amendments, reconsideration and allowance of all claims presently being considered on the merits in the above-identified application are respectfully requested.

To the extent necessary, Applicants hereby petition for an extension of time under 37 CFR 1.136. Kindly charge any shortage of fees due in connection with the filing of this paper, including any extension of time fees, to the Deposit Account of Antonelli, Terry, Stout & Kraus, LLP, Account No. 01-2135 (case 1204.46258X00), and please credit any overpayments to such Deposit Account.

Respectfully submitted,

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